ON Semiconductor



Product Bulletin

Document # :PB21031X Issue Date: 27 August 2015

Title of Change:		-	Change in Carrier Tape Pocket Width (Ao) Dimension for WLCSP8 (0.83x0.65) PTIC Devices manufactured at SSMP Tarlac.				
Effective date:			1 September 2015				
Contact information:			<pre><rul>Rowena.Naigar@onsemi.com><hiroshi2.kobayashi@onsemi.com></hiroshi2.kobayashi@onsemi.com></rul></pre>				
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Type of n	otification:	ON Semico	ON Semiconductor will consider this change accepted.				
Change category:		🗌 Wafer F	Wafer Fab Change Assembly Change Test Change Other <u>Tape and Reel Change</u>				
🗌 Manı	e Sub-Category(ufacturing Site Ch ufacturing Proces	hange/Addition	Material Char	-	 Datasheet/Product Doc change Shipping/Packaging/Marking Other: 		
Sites At	ffected: te(s)	not applicable	pplicable ID ON Semiconductor site(s) : ON Tarlac City, Philippines		External Foundry/Subcon site(s)		
-			ion to minimize de peration at SSMP T New Carrier Tape		the carrier tape pocket. Affected products are WLCSP8	1	
- F	W	8.0 mm	8.0 mm	none			
	T	0.2 mm	0.2 mm	none			
	Ao	0.81 mm	0.78 mm	0.03			
	Во	0.96 mm	0.96 mm	none	40		
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List of Aff	ected Standard	l Parts:					
TCP-3112H-DT							
	2-3127H-DT						
-	2-3133H-DT 2-4012UB-DT						
	-4018UB-DT						
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101	P-4027UB-DT						